

General Description

The 50N06 combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON).

This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

Features

- 55A,60V.RDS(ON)=0.011Ω@VGS=10V
- N-channel-Enhancement mode
- Low Threshold Drive
- 100% Avalanche Tested
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current ¹	55	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current ¹	38	A
I_{DM}	Pulsed Drain Current ²	165	A
EAS	Single Pulse Avalanche Energy ³	94	mJ
I_{AS}	Avalanche Current	38	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	80	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	50	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	2.1	$^\circ\text{C/W}$

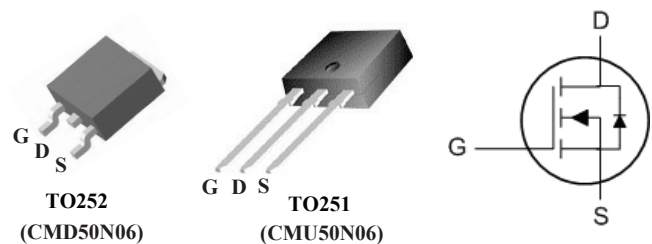
Product Summary

BVDSS	RDSON	ID
60V	11mΩ	55A

Applications

- DC-DC & DC-AC Converters
- Motor Control, Audio Amplifiers
- High Current, High Speed Switching
- Primary Switch for 12V and 24V system

TO252 / TO251 Pin Configuration



TO252
(CMD50N06)

TO251
(CMU50N06)

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=250\mu A$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=250\mu A$	---	0.065	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$, $I_D=55A$	---	10.2	11	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu A$	2	---	4	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=60V$, $V_{GS}=0V$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=60V$, $V_{GS}=0V$, $T_J=125^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V$, $I_D=20A$	---	35	---	S
R_g	Gate Resistance	$V_{DS}=0V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	1.2	---	Ω
Q_g	Total Gate Charge	$V_{DS}=30V$, $V_{GS}=10V$, $I_D=55A$	---	42	---	nC
Q_{gs}	Gate-Source Charge		---	11	---	
Q_{gd}	Gate-Drain Charge		---	8	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V$, $V_G=10V$, $R_G=9.6\Omega$ $I_D=55A$	---	10.5	---	ns
T_r	Rise Time		---	83	---	
$T_{d(off)}$	Turn-Off Delay Time		---	36	---	
T_f	Fall Time		---	32	---	
C_{iss}	Input Capacitance	$V_{DS}=30V$, $V_{GS}=0V$, $f=1\text{MHz}$	6200	7200	---	pF
C_{oss}	Output Capacitance		---	850	---	
C_{rss}	Reverse Transfer Capacitance		---	690	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ¹	$V_G=V_D=0V$, Force Current	---	---	55	A
I_{SM}	Pulsed Source Current ²		---	---	165	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=55A$, $T_J=25^\circ\text{C}$	---	---	1.25	V

Note :

1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.

2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.1mH$, $I_{AS}=36A$